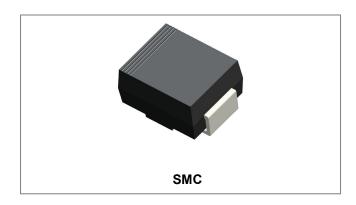






SK310 SCHOTTKY RECTIFIER



Features

- Small foot print, surface mountable
- Very low forward Voltage Drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Green Products in Compliance the ROHS Directive
- This is a Pb Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage	V_{RRM}	-		
Working Peak Reverse Voltage	V_{RWM}		100	V
DC Blocking Voltage	V_R			
Average Rectified Forward Current	1	50% duty cycle @T∟=100°C, rectangular	2	Α
Average Reclined Forward Current	I _F (AV)	wave form	J	^
Peak One Cycle Non-Repetitive	leou.	8.3ms, Half Sine pulse, T _c = 25 °C	110	Α
Surge Current	IFSM	6.5ms, mail Sine pulse, T _c = 25°C	110	^

Electrical Characteristics:

Characteristics	Symbol	Condition	Тур.	Max.	Units
Forward Voltage Drop*	V _{F1}	@ 3A, Pulse, T _J = 25 °C	0.77	0.85	V
	V _{F2}	@ 3A, Pulse, T _J = 125 °C	0.62	0.80	V
Reverse Current*	I _{R1}	@V _R = rated V _R , T _J = 25 °C	0.001	0.6	mA
	I _{R2}	@V _R = rated V _R , T _J = 125 °C	1	20.0	mA
Junction Capacitance	Ст	$@V_R = 5V, T_C = 25 ^{\circ}C, f_{SIG} = 1MHz$	120	250	pF
Series Inductance	L _S	Measured lead to lead 5 mm from package body	8.0	-	nH
Voltage Rate of Change	dv/dt	-	-	10,000	V/μs

^{*} Pulse width < 300 µs, duty cycle < 2%



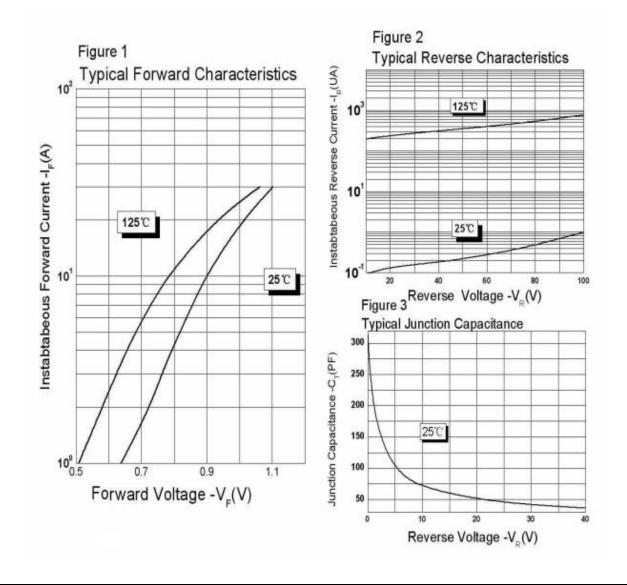




Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	TJ	-	-55 to +150	°C
Storage Temperature	T _{stg}	-	-55 to +150	°C
Typical Thermal Resistance Junction to Lead	$R_{ heta JL}$	DC operation	20	°C/W
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	DC operation	77	°C/W
Approximate Weight	wt	-	0.21	g

Ratings and Characteristics Curves



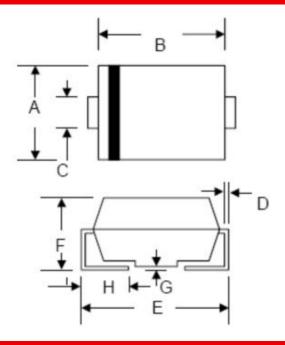
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Mechanical Dimensions SMC



SYMBOL	Millimeters		Inches		
STWIBOL	Min.	Max.	Min.	Max.	
А	5.59	6.22	0.220	0.245	
В	6.60	7.11	0.260	0.280	
С	2.75	3.25	0.108	0.128	
D	0.152	0.305	0.006	0.012	
Е	7.75	8.25	0.305	0.325	
F	2.00	2.95	0.079	0.116	
G	0.051	0.203	0.002	0.008	
Н	0.76	1.60	0.030	0.063	

Ordering Information

Device	Package	Shipping	
SK310	SMC (Pb-Free)	3000pcs / reel	

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



Where XXXXX is YYWWL

 SK
 = Device Type

 3
 = Forward Current (3A)

 10
 = Reverse Voltage (100V)

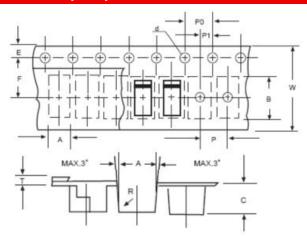
 YY
 = Year

 WW
 = Week

= Lot Number

Cautions: Molding resin Epoxy resin UL:94V-0

Carrier Tape Specification SMC



SYMBOL	Millimeters		
	Min.	Max.	
Α	5.90	6.10	
В	8.20	8.40	
C	2.40	2.60	
d	1.40	1.60	
E	1.40	1.60	
F	7.60	7.70	
Р	7.90	8.10	
P0	3.90	4.10	
P1	3.90	4.10	
Т	-	0.600	
W	15.80	16.20	

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